

### 描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：1.0A，SMA 封装。  
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:1.0A ,SMA package.

### 特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。  
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

### 用途 / Applications

一般用途。  
General purpose.

### 内部等效电路 / Equivalent Circuit

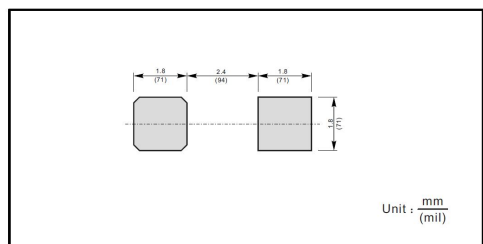


### 引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



### 印章代码 / Marking

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S1A	S1B	S1D	S1G	S1J	S1K	S1M	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	1.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	30							A
Typical Junction Capacitance at $V_R=4V$ $f=1MHz$	$C_j$	15							pF
Typical Thermal Resistance <sup>1)</sup>	$R_{\theta JA}$	75							°C/W
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150							°C

Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5cm) copper pad areas.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S1A	S1B	S1D	S1G	S1J	S1K	S1M	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=1.0A$	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$T_a=25^\circ C$	5.0							$\mu A$
		$T_a=125^\circ C$	50							$\mu A$

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

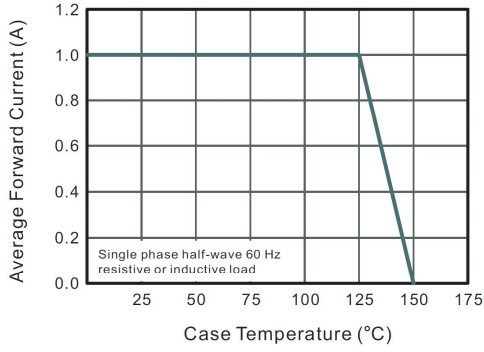


Fig.2 Typical Reverse Characteristics

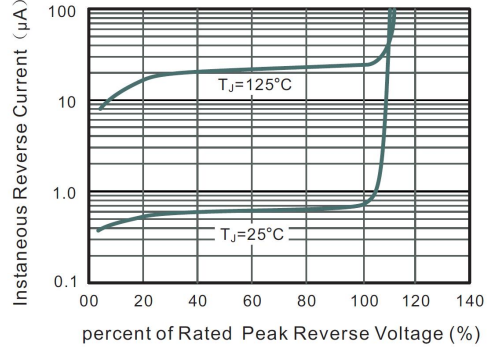


Fig.3 Typical Forward Characteristic

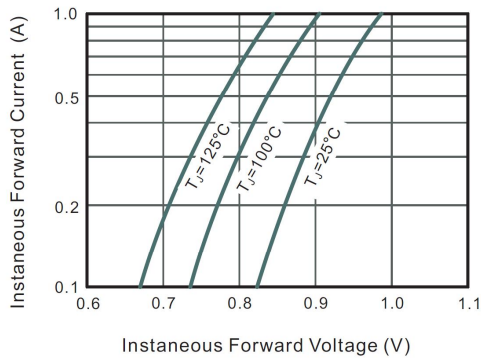


Fig.4 Typical Junction Capacitance

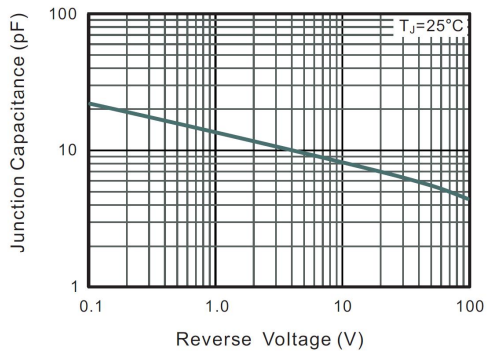
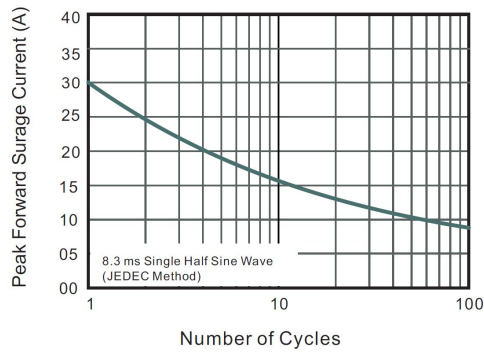
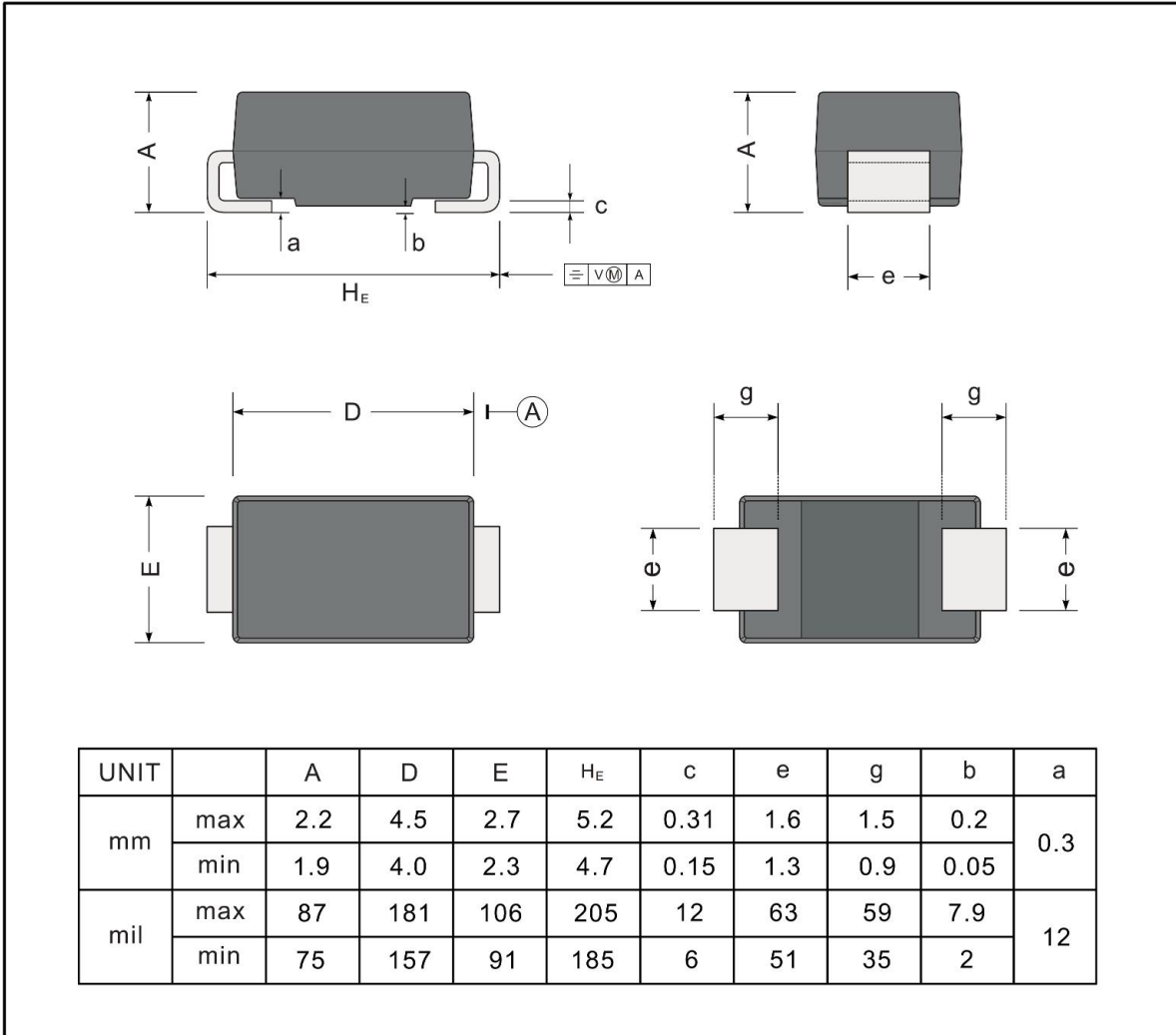


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

SMA



# Marking

Type number	Marking code
S1A	S1A
S1B	S1B
S1D	S1D
S1G	S1G
S1J	S1J
S1K	S1K
S1M	S1M

印章说明 / Marking Instructions



说明：

S1A： 为型号代码

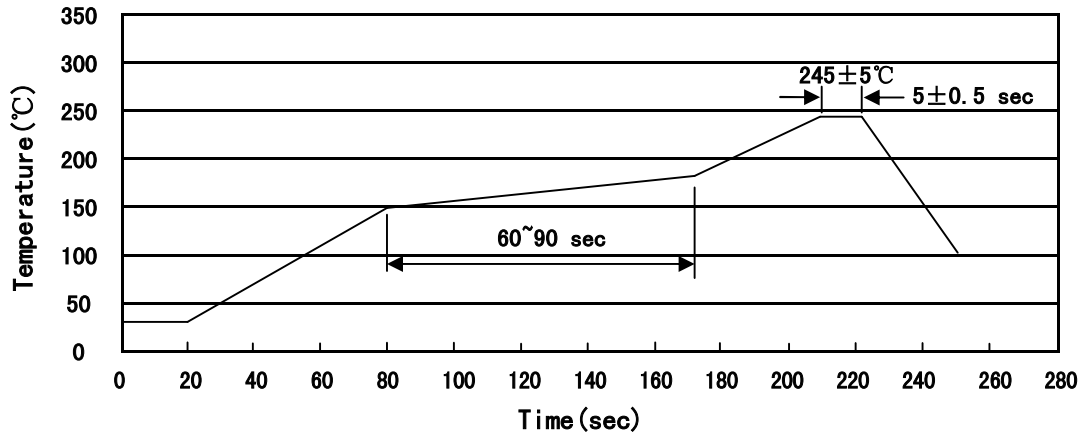
\*\*\*\*： 为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

Note:

S1A： Product Type Code

\*\*\*\*： Lot No. Code ,The 1st \* means:YM Code ,The last 3 \* means:little Lot No  
Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

**使用说明 / Notices**